

800V Super-junction Power MOSFET

Description

800V Super-junction Power MOSFET

Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The Multi-EPI SJ MOSFET provide an extremely low switching, communication and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

Features

- Very low FOM R_{DS(on)} × Q_g
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

Applications

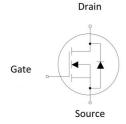
- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Low Power Chargers and Adapters

TO-220F











Device Marking and Package Information

Device	Package	Marking
TPA80R180M	TO-220F	80R180M
TPB80R180M	TO-263	80R180M

Key Performance Parameters

Parameter	Value	Unit
V _{DS} @ T _{j,max}	850	V
R _{DS(on),max}	0.18	Ω
$Q_{g,typ}$	54.9	nC
I _D	23	A
I _{D,pulse}	69	A
E _{OSS} @ 400V	4.95	μJ
Body Diode di _F /dt	500	A/μs



Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted					
Parameter			Symbol	Values	Unit
	T _C = 25°C			23	^
Continuous Drain Current	T _C = 100°C		l _D	13.8	Α
Pulsed Drain Current	(r	note1)	I _{D,pulse}	69	Α
Gate-Source Voltage			V_{GSS}	±30V	V
Single Pulse Avalanche Energy	(n	note2)	E _{AS}	1125	mJ
Repetitive Avalanche Energy	(n	note2)	E_{AR}	27.8	mJ
Avalanche Current		I _{AR}	4.6	Α	
MOSFET dv/dt Ruggedness, V _{DS} = 0480V		dv/dt	50	V/ns	
Power Dissipation For TO-220F			P_{D}	44.6	W
Power Dissipation For TO-263				215	
Continuous Diode Forward Current			I _S	20	_
Diode Pulsed Current (note1)		I _{S,pulse}	69	Α	
Reverse Diode dv/dt (note3)		dv/dt	15	V/ns	
Maximum Diode Commutation Speed (note3)		di _f /dt	500	A/µs	
Operating Junction and Storage Temperature Range		T_J,T_stg	-55~+150	°C	

Thermal Resistance For TO-220F				
Parameter Symbol Value U				
Thermal Resistance, Junction-to-Case	R _{thJC}	2.8	°C/W	
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5	-0/00	

Thermal Resistance For TO-263				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R _{thJC}	0.59	°C/W	
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5	C/VV	

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Electrical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted							
D		Total Octobbility	Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	800			V	
		$V_{DS} = 800V$, $V_{CS} = 0V$, $T_{L} = 25^{\circ}C$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0V, T_{J} = 25^{\circ}C$ $V_{DS} = 800V,$ $V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μΑ	
Gate-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.5	V	
Drain-Source On-State-Resistance	R _{DS(on)}	V _{GS} = 10V,I _D = 11.5A		0.16	0.18	Ω	
Gate Resistance	R_{G}	f = 1.0MHz open drain		1.5		Ω	
Dynamic Characteristics							
Input Capacitance	C _{iss}	V = 0V		2468.4			
Output Capacitance	C _{oss}	$V_{GS} = 0V$, $V_{DS} = 100V$		56.81		pF	
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		5.2			
Total Gate Charge	Q_g	V = 640V		54.9			
Gate-Source Charge	Q_{gs}	$V_{DD} = 640V,$ $I_{D} = 23A,$		10.4		nC	
Gate-Drain Charge	Q_{gd}	V _{GS} = 10V		21.5			
Turn-on Delay Time	t _{d(on)}			68.45			
Turn-on Rise Time	t _r	V _{DD} = 400V		76.9			
Turn-off Delay Time	$t_{d(off)}$	$I_D = 23A$ $R_G = 25\Omega$		180.2		ns	
Turn-off Fall Time	t _f			58.35			
Drain-Source Body Diode Characte	ristics						
Body Diode Forward Voltage	V_{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 12A$, $V_{GS} = 0V$		0.9	1.2	V	
Reverse Recovery Time	t _{rr}	V = 400		405.4		ns	
Reverse Recovery Charge	Q _{rr}	$V_{R} = 400$ $I_{F} = 20A$		4.633		μC	
Peak Reverse Recovery Current	I _{rrm}	$di_F/dt = 100A/\mu s$		22.83		Α	

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. $I_D = 10A$, $V_{DD} = 50V$, $R_G = 25\Omega$, Starting $T_J = 25$ °C
- 3. Identical low side and high side switch with identical ${\rm R}_{\rm G}$



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

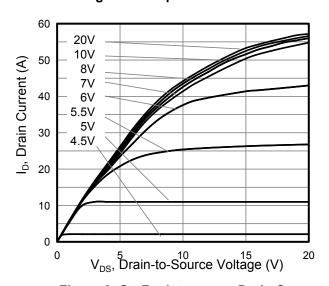


Figure 3. On-Resistance vs. Drain Current

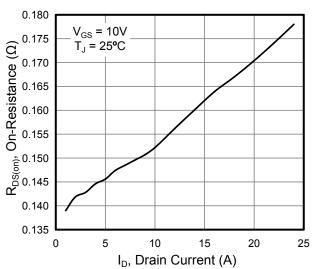


Figure 5. Gate Charge

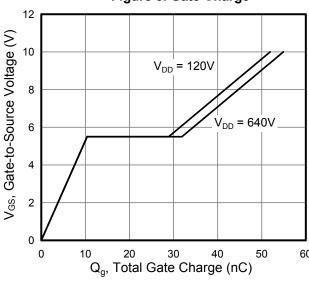


Figure 2. Transfer Characteristics

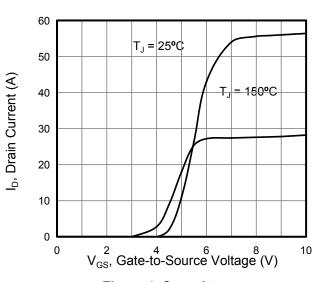


Figure 4. Capacitance

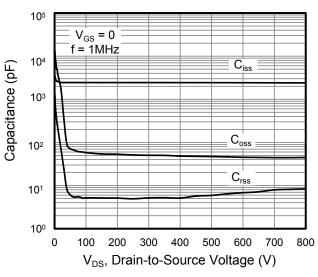
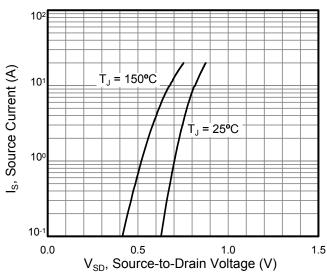


Figure 6. Body Diode Forward Voltage



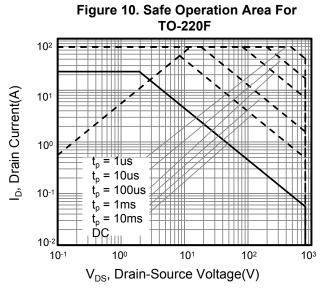


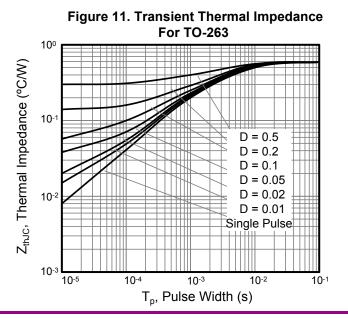
Typical Characteristics T_J = 25°C, unless otherwise noted

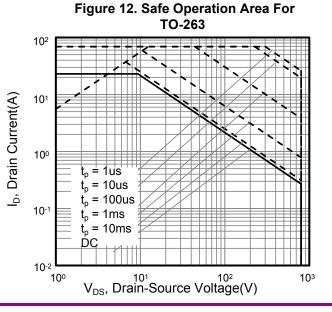
Figure 7. On-Resistance vs. Temperature 3.0 $V_{GS} = 10V$ 2.5 $I_D = 2A$ RDS(ON), (Normalized) 2.0 1.5 1.0 0.5 0.0 0 25 50 -50 -25 75 100 125 150 T_J, Junction Temperature (°C)

Figure 8. Breakdown Voltage vs. **Junction Temperature** 1.3 $I_D = 250 \mu A$ 1.2 V_{BR(DSS)}, (Normalized) 1.1 1.0 0.9 8.0 -25 25 50 75 150 -50 0 100 125 T_J, Junction Temperature (°C)

Figure 9. Transient Thermal Impedance For **TO-220F** 5 Z_{thJC}, Thermal Impedance (°C/W) 100 D = 0.510-1 D = 0.05D = 0.0210-2 D = 0.01Single Pulse 10-3 10-1 10-5 10-4 10-2 10¹ 10² T_p, Pulse Width (s)









Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

Figure 13. Typ. Coss Stored Energy

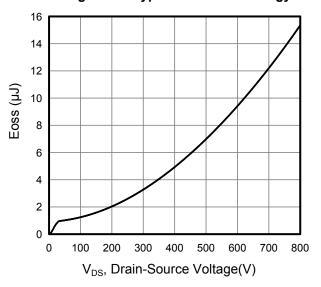




Figure A: Gate Charge Test Circuit and Waveform

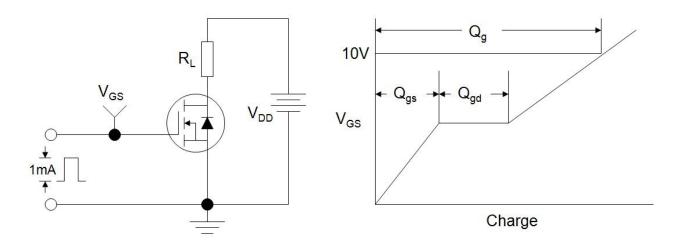


Figure B: Resistive Switching Test Circuit and Waveform

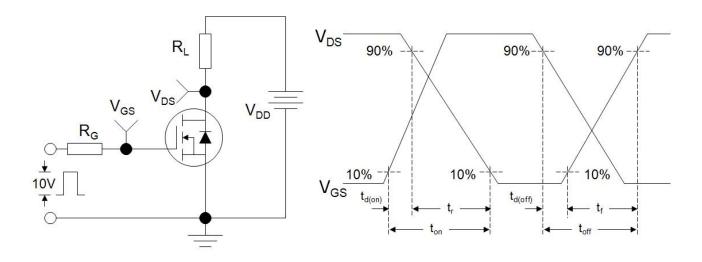
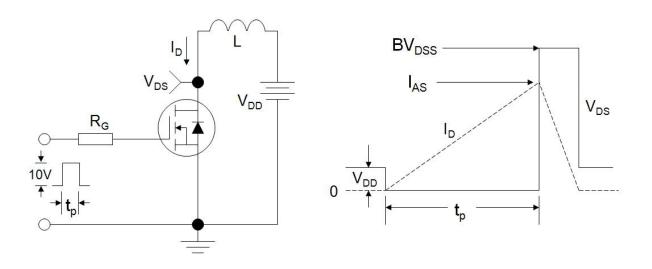


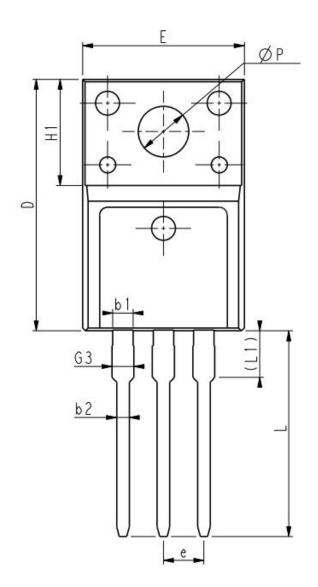
Figure C: Unclamped Inductive Switching Test Circuit and Waveform

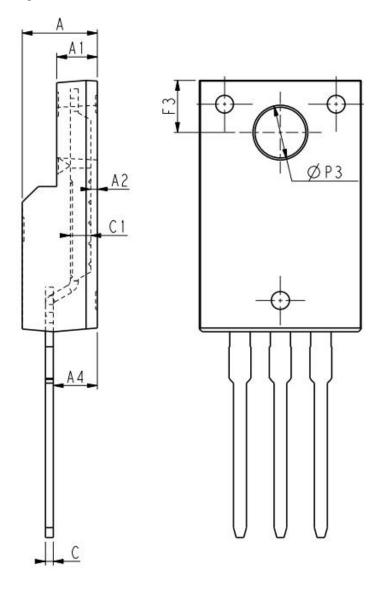


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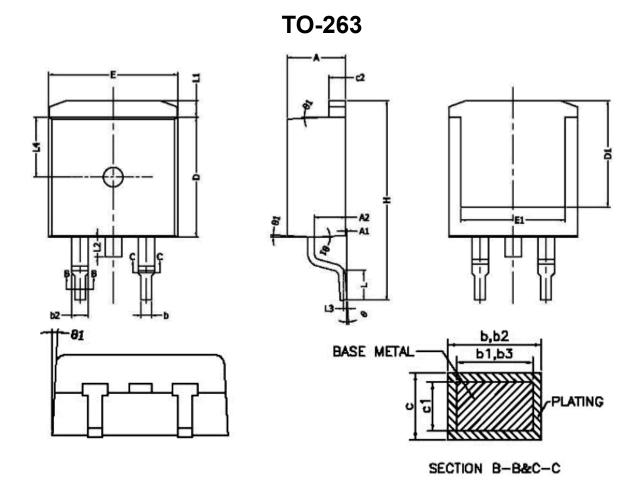
TO-220F





Unit:mm				
Symbol	Min.	Nom	Max.	
Е	9.96	10.16	10.36	
А	4.50	4.70	4.90	
A1	2.34	2.54	2.74	
A2	0.30	0.45	0.60	
A4	2.56	2.76	2.96	
С	0.40	0.50	0.65	
c1	1.20	1.30	1.35	
D	15.57	15.87	16.17	
H1	6.70REF			

Unit:mm				
Symbol	Min.	Nom	Max.	
е		2.54BSC		
L	12.68	12.98	13.28	
L1	2.93	3.03	3.13	
ФР	3.03	3.18	3.38	
ФР3	3.15	3.45	3.65	
F3	3.15	3.30	3.45	
G3	1.25	1.35	1.55	
b1	1.18	1.28	1.43	
b2	0.70	0.80	0.95	



SYMBOL	MIN	NOM	MAX	
Α	4.40	4.50	4.60	
A1	0	0.10	0.25	
A2	2.20	2.40	2.60	
b	0.76		0.89	
b1	0.75	0.80	0.85	
b2	1.23		1.37	
b3	1.22	1.27	1.32	
С	0.47		0.60	
c1	0.46	0.51	0.56	
c2	1.25	1.30	1.35	
D	9.10	9.20	9.30	
D1	8.00			
E	9.80	9.90	10.00	
E1	7.80			
е	2.	54 BSC		
Н	14.90	15.30	15.70	
L	2.00	2.30	2.60	
L1	1.17	1.27	1.40	
L2			1.75	
L3	0.25BSC			
L4	4.60 REF			
θ	00	1	8°	
0 1	1°	3°	5°	

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